

Product Advisory

Issue Date: Dec 10, 2020**Change Type:**

Addition of ASESH (Shanghai), an approved Broadcom assembly site within the ASE group.

Parts Affected:

BCM53134UKFBG	BCM53134OKFBG	BCM53134PKFBG
BCM53134SKFBG	BCM53134MKFBG	BCM53134OIFBG
BCM53134SIFBG	BCM53134MIFBG	BCM53134PIFBG

Description and Extent of Change:

Addition of assembly of 11X11 FBGA package at ASESH (Shanghai).
No change to Form, FIT, Function and Reliability.

Reasons for Change:

Manufacturing flexibility is needed to meet demand.

Effect of Change on Fit, Form, Function, Quality, or Reliability:

The device specification will remain the same, which will ensure product electrical performance remains the same. Appropriate electrical characterization and reliability qualification has been performed on representative products to ensure normal parametric distribution, consistent electrical performance, and reliability.

Effective Date of Change:

Both site will ship interchangeably and is targeted to ship Dec/11/2020. The timing of shipments will vary by part number, depending on customer demand and inventory levels.

Qualification Data:

- ASESH is Qualified Broadcom site for FBGA package and these devices have been qualified
- FBGA 10X10 and 21x21 is currently shipping in volume production from ASESH
- BCM58101B0KFBG, and BCM58202 are qualified and currently shipping from ASESH

Please reference table below.

Stress Test	Condition	Read points	Sample Size	Requirements	Results
		Cycles / Hrs.			
Precondition	MSL3 JESD22-A113E		154 units	0 failures	0 / 154
Temp Cycle	-55°C / 125°C JEDEC Std. 22-A104-C Cond. B	1000 cycles	77 units	0 failures	0 / 77
uHast	130°C/85%RH JEDEC Std. 22-A102-C	96hrs	77 units	0 failures	0 / 77
HTSL	TA=150°C	1000hrs	77 units	0 failures	0 / 77

Please contact your Broadcom field sales engineer or Contact Center for any questions or support requirements. Please return any response as soon as possible, but not to exceed 30 days.